Session Title:	[ThA1] Functional Wet Etching Technology
Session Date:	November 14 (Thu.), 2024
Session Time:	09:00-10:30
Session Room:	Room A (Capri Room, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Kangchun Lee (Kyonggi Univ., Korea)

[ThA1-1] [Invited] 09:00-09:25

Breakthrough Additive Technology for Cu Post-CMP Cleaning Solutions in Semiconductor Processes: Achieving Selective CuO Etching

Sangseung Park, Narea Yim, Hag Sung Lee, Ga Young Kim, Bo Yeon Lee, and Myung Geun Song (ENF Tech. Co., Ltd., Korea)

[ThA1-2] [Invited] 09:25-09:50

Highly Selective Etching for 3D Semiconductor Architecture

Sangwoo Lim (Yonsei Univ., Korea)

[ThA1-3] 09:50-10:10

Mechanism of Polymeric Inhibiting Layer in Wet Etchant for Highly Selective Etching of Si1-xGex- to Si-Film

Chang-Jin Lee, Eun-Woo Jang, and Jea-Gun Park (Hanyang Univ., Korea)

[ThA1-4] 10:10-10:30

Effect of pH and Dissolved Oxygen Levels on the Efficiency of Corrosion Inhibitors for Molybdenum during the CMP Process

Palwasha Jalalzai, Nayoung Kang, Manilal Murmu, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)